

LISTING OF CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

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- C1
1. (Currently Amended) A device enclosure comprising:  
a chassis including a top wall and an opposing bottom wall; and  
a [detachable] thermo-siphon device formed as an integral part of [a] the top wall of the chassis, the thermo-siphon device including first heat pipe and a second heat pipe, a vaporizing end of the first and second heat pipe coupled to a first metal plate, a condensing end of the first heat pipe coupled to a second metal plate, and a condensing end of the second heat pipe coupled to a third metal plate.
  2. (Original) The device of claim 1, wherein the device is an electronic device.
  3. (Original) The device of claim 2, wherein the device enclosure is a computer chassis.
  4. (Original) The device of claim 1, wherein the device is a non-electronic device.
  5. <sup>/</sup>  
Canceled.
  6. <sup>/</sup>  
Canceled.
  9. (Previously Amended) The device of claim 1, wherein the wall is fabricated from a metallic material.

10. (Previously Amended) The device of claim 1, wherein the thermo-siphon device is embedded in a cavity of the wall.

11. (Previously Amended) The device of claim 10, wherein the cavity is created during a fabrication process of the wall.

12. (Previously Amended) The device of claim 1, wherein the wall partially encloses the thermo-siphon device.

13. (Original) The device of claim 12, wherein a portion of the thermo-siphon device is exposed to an interior of the enclosure.

14. (Original) The device of claim 12, wherein a portion of the thermo-siphon device is exposed to a heat sink.

17. (Previously Amended) The device of claim 1, wherein the thermo-siphon device is secured to a wall cavity through the means selected from the group consisting of a support provided by cavity walls, a thermal epoxy, and an interference fit with the wall cavity.

18. Canceled.

19. (Currently Amended) A system comprising:

a chassis including a top wall and an opposing bottom wall; and  
a [detachable] thermo-siphon device formed as an integral part of [a] the top wall of the chassis, the thermo-siphon device including first heat pipe and a second heat pipe, a vaporizing end of the first and second heat pipe coupled to a first metal plate, a condensing end of the first heat pipe coupled to a second

metal plate, and a condensing end of the second heat pipe coupled to a third metal plate..

20. Canceled.

21. Canceled.

22. (Original) The system of claim 19, wherein the chassis is a computer chassis.

24. (Previously Amended) A computer chassis comprising:  
a chassis including a top wall and an opposing bottom wall; and  
a [detachable] thermo-siphon device formed as an integral part of [a] the top wall of the chassis, the thermo-siphon device including first heat pipe and a second heat pipe, a vaporizing end of the first and second heat pipe coupled to a first metal plate, a condensing end of the first heat pipe coupled to a second metal plate, and a condensing end of the second heat pipe coupled to a third metal plate.

25. Canceled.

26. (Original) The computer chassis of claim 24, wherein the computer chassis is a notebook computer base.

28. (Previously Amended) The computer chassis of claim 24, wherein the thermo-siphon device is embedded in the wall during the manufacturing process of the skin.